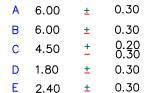
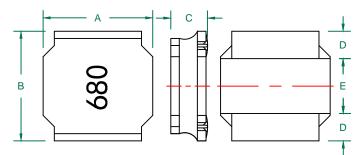
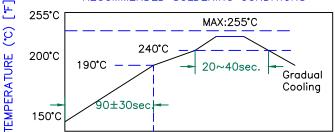
TYS6045680M-10

PHYSICAL DIMENSIONS:

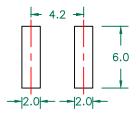


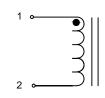


RECOMMENDED SOLDERING CONDITIONS



LAND PATTERNS FOR REFLOW SOLDERING

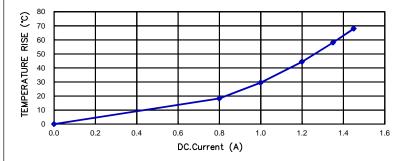




ELECTRICAL SPECIFICATION

	Min	Nom	Max
INDUCTANCE (uH) L @ 100 KHz/1V ± 20%	54.4	68.0	81.6
DCR (Ω)		0.289	0.3757

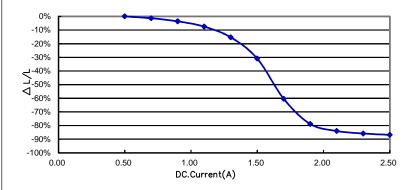
CHARACTERISTICS OF TEMPERATURE RISE





Saturation Current(A)	1.20
SRF (MHz)	6.4
Temperature Rise Current (A)	1.00

CURRENT VS INDUCTANCE DROP IN RATES



NOTES:

- 1.OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
- 2.STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): -10°C TO +40°C AND RH 70% (MAX.)
- 3.UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
 A. AMBIENT TEMPERATURE: 201150.
- B. RELATIVE HUMIDITY: 65%±20%.
- 4.SATURATION CURRENT IS THE DC CURRENT AT WHICH THE INDUCTANCE DROPS OFF APPROXIMATELY 30% FROM ITS VALUE WITHOUT CURRENT.(AMBIENT TEMPERATURE 25±5°C)
- 5. TEMPERATURE RISE CURRENT (IRMS):

DC CURRENT THAT CAUSES THE TEMPERATURE RISE (△T ≤40°C) FROM 25°C AMBIENT.

		DIMENSIONS ARE IN mm .			This print is the property of Lair Tech. and is loaned in confidence subject to return upon request c with the understanding that no copies shall be made without the written consent of Laird Tech. Al rights to design or invention are reserved.	Laird				
ı					PROJECT/PART NUMBER:	- 1.	EV	PART TO		DRAWN BY:
	С	CHANGE DIMENSIONS C/D/E	08/18/16	_	TYS6045680M-10	1	С		WER CTOR	QIU
	В	CHANGE TEMP FROM −25°C~+125°C	12/24/12	QIU	DATE: 05/08/12	SCALI	NIS		SHEET:	
	Α	ORIGINAL DRAFT	05/08/12	QIU		TOOL				
	REV	DESCRIPTION	DATE	INT			-		1	of 1